

Figure 1

Lercei
BUR920010177US1
Sheet 2 of 6



Figure 2

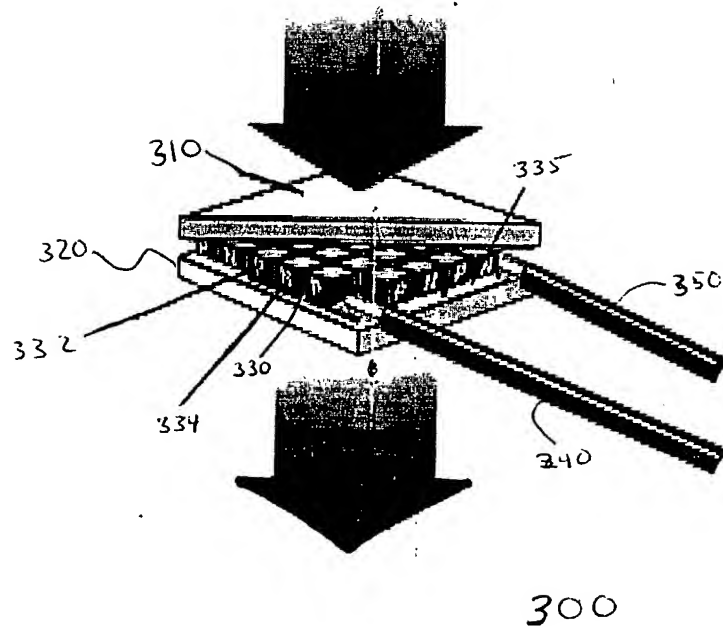


Figure 3

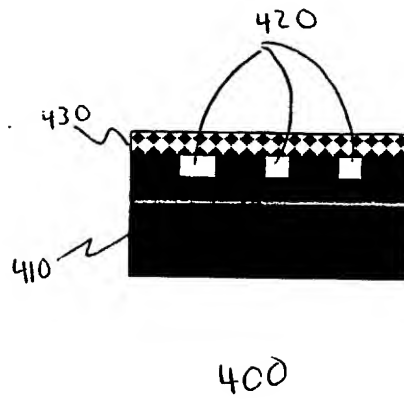


Figure 4

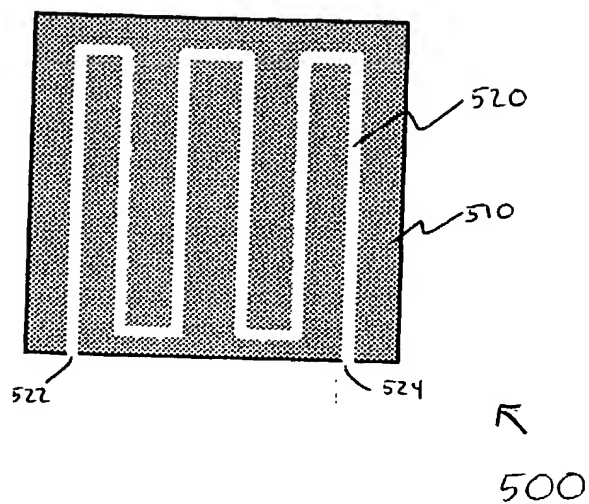


Figure 5

Material	Coefficient of Thermal Expansion (parts per million per degree Celsius)	Thermal Conductivity (W/m K)
Pyrex	3.25	2
Borosilicate Glass (low expansion)	3.25	1.1
Silicon	2.6	156
Diamond	2.7	1000
SiC (sintered)	4.4	150

Figure 6